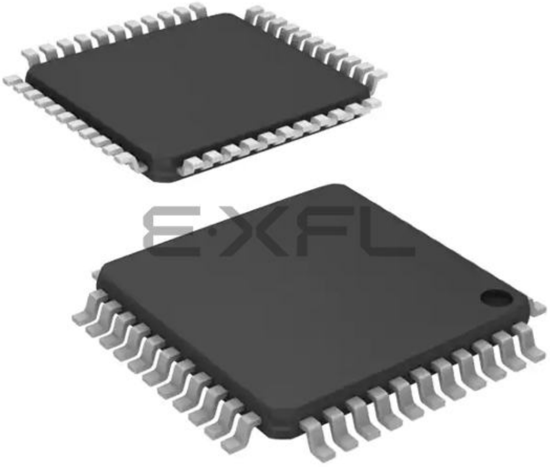
Microchip Technology - DSPIC33EV128GM104T-I/PT Datasheet



What is "Embedded - Microcontrollers"?

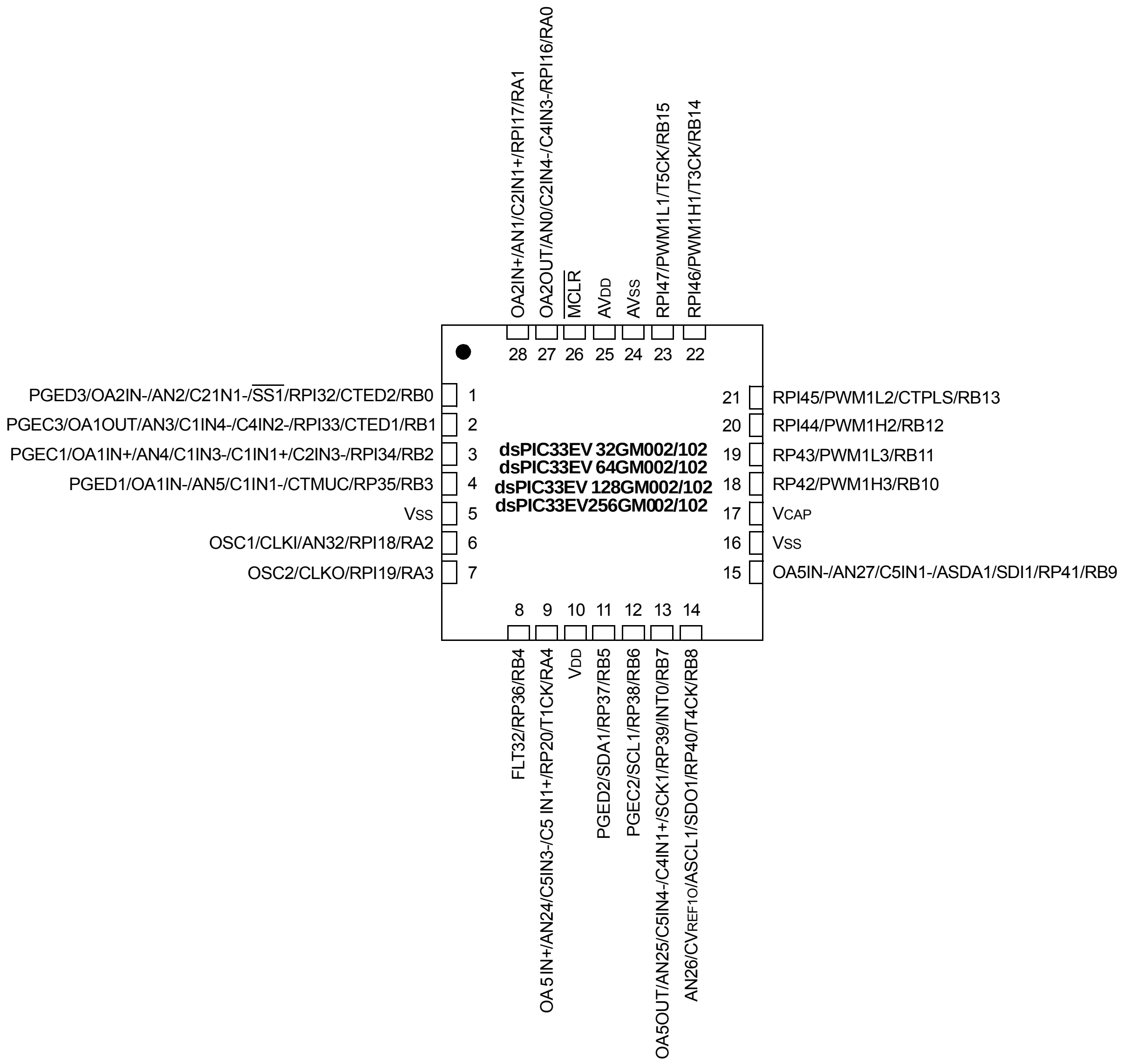
"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	70 MIPs
Connectivity	CANbus, I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	35
Program Memory Size	128KB (43K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 24x10/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ev128gm104t-i-pt

Pin Diagrams (Continued)

28-Pin QFN-S$^{(1,2,3,4)}$



Note 1: The RPn/RPIn pins can be used by any remappable peripheral with some limitation. See **Section 11.5 “Peripheral Pin Select (PPS)”** for available peripherals and information on limitations.

2: Every I/O port pin (RAx-RGx) can be used as a Change Notification pin (CNAx-CNGx). See **Section 11.0 “I/O Ports”** for more information.

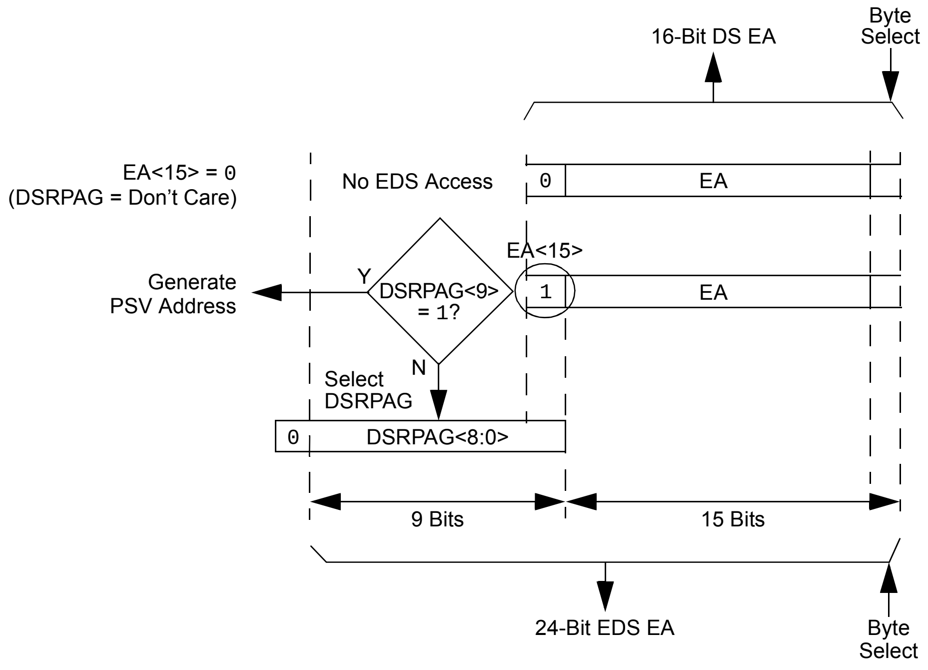
3: If the op amp is selected when OPAEN (CMxCON<10>) = `1`, the OAx input is used; otherwise, the ANx input is used.

4: The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

4.3.1 PAGED MEMORY SCHEME

The dsPIC33EVXXXGM00X/10X family architecture extends the available DS through a paging scheme, which allows the available DS to be accessed using `MOV` instructions in a linear fashion for pre- and post-modified Effective Addresses (EAs). The upper half of the Base Data Space address is used in conjunction with the Data Space Page registers, the 10-bit Data Space Read Page register (DSRPAG) or the 9-bit Data Space Write Page register (DSWPAG), to form an EDS address, or Program Space Visibility (PSV) address. The Data Space Page registers are located in the SFR space. Construction of the EDS address is shown in Figure 4-9 and Figure 4-10. When DSRPAG<9> = `0` and the base address bit, EA<15> = `1`, the DSRPAG<8:0> bits are concatenated onto EA<14:0> to form the 24-bit EDS read address. Similarly, when the base address bit, EA<15> = `1`, the DSWPAG<8:0> bits are concatenated onto EA<14:0> to form the 24-bit EDS write address.

FIGURE 4-9: EXTENDED DATA SPACE (EDS) READ ADDRESS GENERATION



Note: DS read access when DSRPAG = 0x000 will force an address error trap.

REGISTER 8-3: DMAxSTAH: DMA CHANNEL x START ADDRESS REGISTER A (HIGH)

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
STA<23:16>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-8	**Unimplemented:** Read as ‘0’
bit 7-0	**STA<23:16>:** DMA Primary Start Address bits (source or destination)

REGISTER 8-4: DMAxSTAL: DMA CHANNEL x START ADDRESS REGISTER A (LOW)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
STA<15:8>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
STA<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0	**STA<15:0>:** DMA Primary Start Address bits (source or destination)

REGISTER 8-14: DMAPPS: DMA PING-PONG STATUS REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	R-0	R-0	R-0	R-0
—	—	—	—	PPST3	PPST2	PPST1	PPST0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-4	**Unimplemented:** Read as ‘`0`’
bit 3	**PPST3:** Channel 3 Ping-Pong Mode Status Flag bit `1` = DMA3STB register is selected `0` = DMA3STA register is selected
bit 2	**PPST2:** Channel 2 Ping-Pong Mode Status Flag bit `1` = DMA2STB register is selected `0` = DMA2STA register is selected
bit 1	**PPST1:** Channel 1 Ping-Pong Mode Status Flag bit `1` = DMA1STB register is selected `0` = DMA1STA register is selected
bit 0	**PPST0:** Channel 0 Ping-Pong mode Status Flag bit `1` = DMA0STB register is selected `0` = DMA0STA register is selected

REGISTER 11-16: RPINR44: PERIPHERAL PIN SELECT INPUT REGISTER 44

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
SENT1R<7:0>							
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-8 **SENT1R<7:0>:** Assign SENT Module Input 1 to the Corresponding RPn Pin bits (see Table 11-2 for input pin selection numbers)

`10110101` = Input tied to RPI181
•
•
•
`00000001` = Input tied to CMP1
`00000000` = Input tied to VSS

bit 7-0 **Unimplemented:** Read as ‘0’

REGISTER 11-17: RPINR45: PERIPHERAL PIN SELECT INPUT REGISTER 45

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
SENT2R<7:0>							
bit 7							bit 0

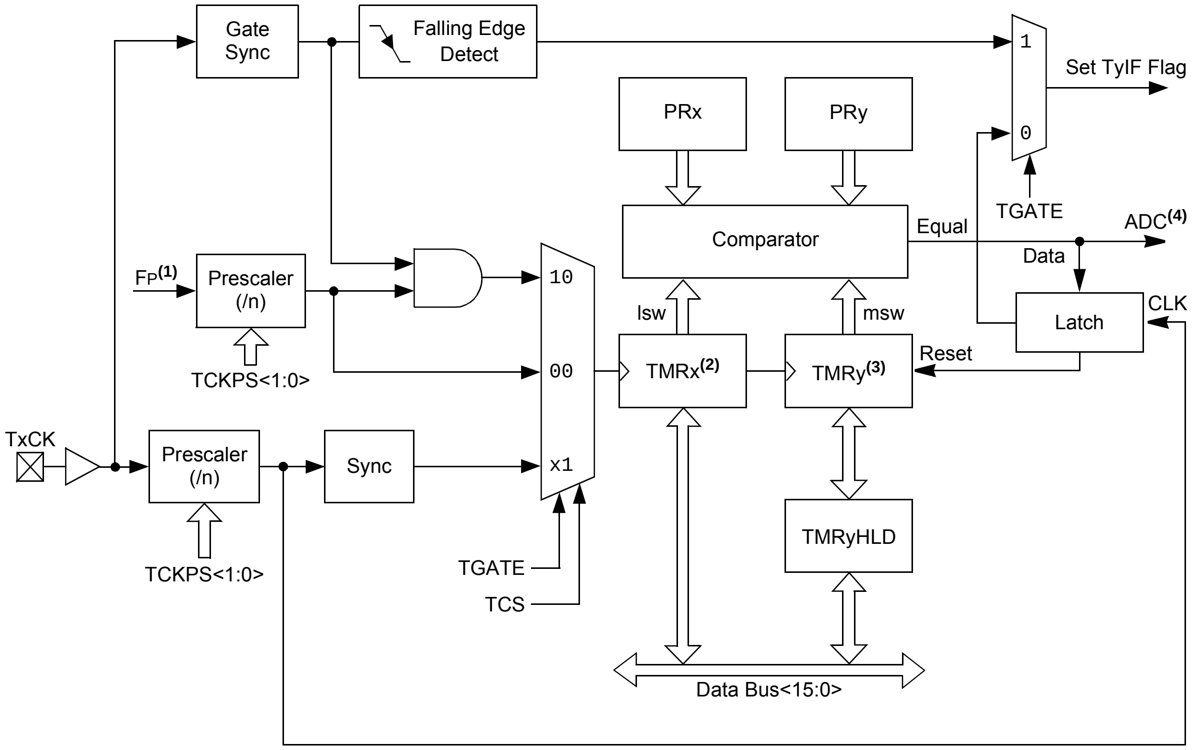
Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-8 **Unimplemented:** Read as ‘0’

bit 7-0 **SENT2R<7:0>:** Assign SENT Module Input 2 to the Corresponding RPn Pin bits (see Table 11-2 for input pin selection numbers)

`10110101` = Input tied to RPI181
•
•
•
`00000001` = Input tied to CMP1
`00000000`= Input tied to VSS

FIGURE 13-3: TYPE B/TYPE C TIMER PAIR BLOCK DIAGRAM (32-BIT TIMER)



Note 1: FP is the peripheral clock.
2: Timerx is a Type B timer (x = 2 and 4).
3: Timery is a Type C timer (y = 3 and 5).
4: The ADC trigger is available only on the TMR3:TMR2 and TMR5:TMR4 32-bit timer pairs.

REGISTER 14-9: DMTPSINTVL: DMT POST CONFIGURE INTERVAL STATUS REGISTER LOW

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PSINTV<15:8>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PSINTV<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0	**PSINTV<15:0>:** Lower DMT Window Interval Configuration Status bits This is always the value of the FDMTINTVL Configuration register.

REGISTER 14-10: DMTPSINTVH: DMT POST CONFIGURE INTERVAL STATUS REGISTER HIGH

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PSINTV<31:24>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PSINTV<23:16>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0	**PSINTV<31:16>:** Higher DMT Window Interval Configuration Status bits This is always the value of the FDMTINTVH Configuration register.

15.0 INPUT CAPTURE

Note 1: This data sheet summarizes the features of the dsPIC33EVXXXGM00X/10X family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Input Capture"** (DS70000352) in the *"dsPIC33/PIC24 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

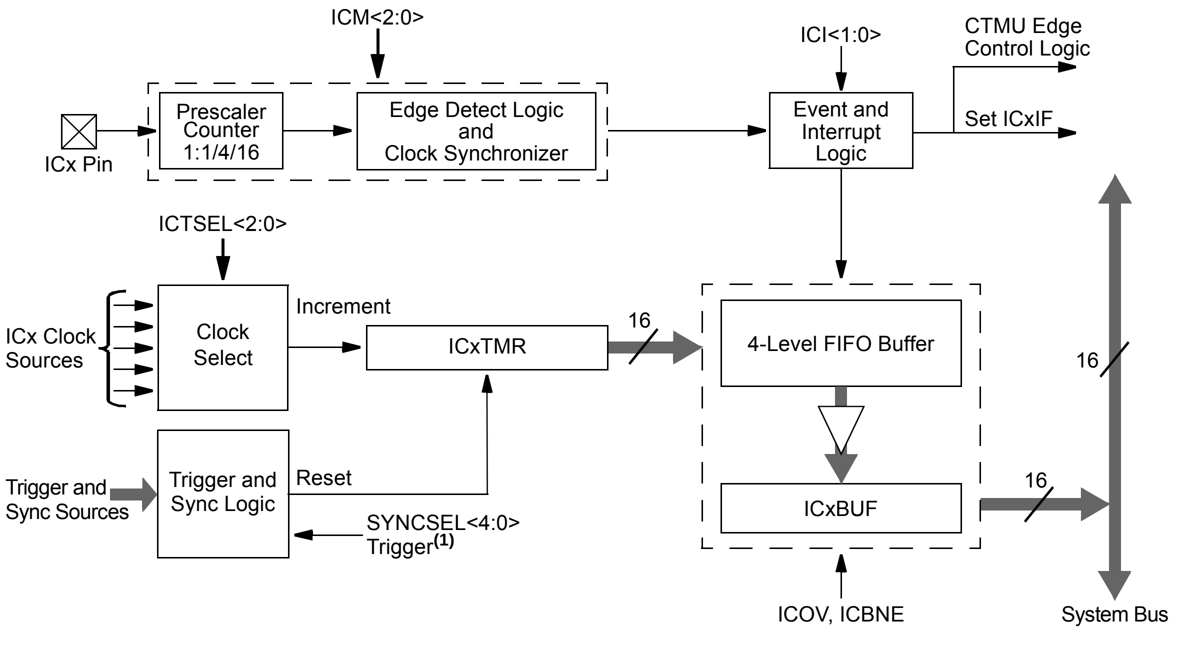
The input capture module is useful in applications requiring frequency (period) and pulse measurement. The dsPIC33EVXXXGM00X/10X family devices support 4 input capture channels.

Key features of the input capture module include:

- Hardware-Configurable for 32-Bit Operation in All Modes by Cascading Two Adjacent modules
- Synchronous and Trigger Modes of Output Compare Operation, with up to 31 User-Selectable Trigger/Sync Sources Available
- A 4-Level FIFO Buffer for Capturing and Holding Timer Values for Several Events
- Configurable Interrupt Generation
- Up to Six Clock Sources Available for Each Module, Driving a Separate Internal 16-Bit Counter

Figure 15-1 shows a block diagram of the Input capture module.

FIGURE 15-1: INPUT CAPTURE x MODULE BLOCK DIAGRAM



Note 1: The trigger/sync source is enabled by default and is set to Timer3 as a source. This timer must be enabled for proper ICx module operation or the trigger/sync source must be changed to another source option.

REGISTER 16-1: OCxCON1: OUTPUT COMPARE x CONTROL REGISTER 1 (CONTINUED)

bit 2-0 **OCM<2:0>:** Output Compare x Mode Select bits

`111` = Center-Aligned PWM mode: Output sets high when OCxTMR = OCxR and sets low when OCxTMR = OCxRS[1]
`110` = Edge-Aligned PWM mode: Output sets high when OCxTMR = `0` and sets low when OCxTMR = OCxR[1]
`101` = Double Compare Continuous Pulse mode: Initializes OCx pin low, toggles OCx state continuously on alternate matches of OCxR and OCxRS
`100` = Double Compare Single-Shot mode: Initializes OCx pin low, toggles OCx state on matches of OCxR and OCxRS for one cycle
`011` = Single Compare mode: Compare event with OCxR, continuously toggles OCx pin
`010` = Single Compare Single-Shot mode: Initializes OCx pin high, compare event with OCxR, forces OCx pin low
`001` = Single Compare Single-Shot mode: Initializes OCx pin low, compare event with OCxR, forces OCx pin high
`000` = Output compare channel is disabled

Note 1: OCxR and OCxRS are double-buffered in PWM mode only.

17.3 PWMx Control Registers

REGISTER 17-1: PTCON: PWMx TIME BASE CONTROL REGISTER

R/W-0	U-0	R/W-0	HS-0, HC	R/W-0	R/W-0	R/W-0	R/W-0
PTEN	—	PTSIDL	SESTAT	SEIEN	EIPU[(1)]	SYNCPOL[(1)]	SYNCOEN[(1)]
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
SYNCEN[(1)]	SYNCSRC2[(1)]	SYNCSRC1[(1)]	SYNCSRC0[(1)]	SEVTPS3[(1)]	SEVTPS2[(1)]	SEVTPS1[(1)]	SEVTPS0[(1)]
bit 7							bit 0

Legend:	HC = Hardware Clearable bit	HS = Hardware Settable bit	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **PTEN:** PWMx Module Enable bit
1 = PWMx module is enabled
0 = PWMx module is disabled

bit 14 **Unimplemented:** Read as ‘0’

bit 13 **PTSIDL:** PWMx Time Base Stop in Idle Mode bit
1 = PWMx time base halts in CPU Idle mode
0 = PWMx time base runs in CPU Idle mode

bit 12 **SESTAT:** Special Event Interrupt Status bit
1 = Special event interrupt is pending
0 = Special event interrupt is not pending

bit 11 **SEIEN:** Special Event Interrupt Enable bit
1 = Special event interrupt is enabled
0 = Special event interrupt is disabled

bit 10 **EIPU:** Enable Immediate Period Updates bit[(1)]
1 = Active Period register is updated immediately
0 = Active Period register updates occur on PWMx cycle boundaries

bit 9 **SYNCPOL:** Synchronize Input and Output Polarity bit[(1)]
1 = SYNCI1/SYNCO1 polarity is inverted (active-low)
0 = SYNCI1/SYNCO1 is active-high

bit 8 **SYNCOEN:** Primary Time Base Sync Enable bit[(1)]
1 = SYNCO1 output is enabled
0 = SYNCO1 output is disabled

bit 7 **SYNCEN:** External Time Base Synchronization Enable bit[(1)]
1 = External synchronization of primary time base is enabled
0 = External synchronization of primary time base is disabled

Note 1: These bits should be changed only when PTEN = 0. In addition, when using the SYNCI1 feature, the user application must program the Period register with a value that is slightly larger than the expected period of the external synchronization input signal.

REGISTER 17-3: PTPER: PWMx PRIMARY MASTER TIME BASE PERIOD REGISTER

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
PTPER<15:8>							
bit 15							bit 8

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-0	R/W-0	R/W-0
PTPER<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0	**PTPER<15:0>:** Primary Master Time Base (PMTMR) Period Value bits

REGISTER 17-4: SEVTCMP: PWMx PRIMARY SPECIAL EVENT COMPARE REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
SEVTCMP<15:8>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
SEVTCMP<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0	**SEVTCMP<15:0>:** Special Event Compare Count Value bits

29.0 DEVELOPMENT SUPPORT

The PIC® microcontrollers (MCU) and dsPIC® digital signal controllers (DSC) are supported with a full range of software and hardware development tools:

- Integrated Development Environment
  - MPLAB® X IDE Software
- Compilers/Assemblers/Linkers
  - MPLAB XC Compiler
  - MPASM™ Assembler
  - MPLINK™ Object Linker/ MPLIB™ Object Librarian
  - MPLAB Assembler/Linker/Librarian for Various Device Families
- Simulators
  - MPLAB X SIM Software Simulator
- Emulators
  - MPLAB REAL ICE™ In-Circuit Emulator
- In-Circuit Debuggers/Programmers
  - MPLAB ICD 3
  - PICkit™ 3
- Device Programmers
  - MPLAB PM3 Device Programmer
- Low-Cost Demonstration/Development Boards, Evaluation Kits and Starter Kits
- Third-party development tools

29.1 MPLAB X Integrated Development Environment Software

The MPLAB X IDE is a single, unified graphical user interface for Microchip and third-party software, and hardware development tool that runs on Windows®, Linux and Mac OS® X. Based on the NetBeans IDE, MPLAB X IDE is an entirely new IDE with a host of free software components and plug-ins for high-performance application development and debugging. Moving between tools and upgrading from software simulators to hardware debugging and programming tools is simple with the seamless user interface.

With complete project management, visual call graphs, a configurable watch window and a feature-rich editor that includes code completion and context menus, MPLAB X IDE is flexible and friendly enough for new users. With the ability to support multiple tools on multiple projects with simultaneous debugging, MPLAB X IDE is also suitable for the needs of experienced users.

Feature-Rich Editor:

- Color syntax highlighting
- Smart code completion makes suggestions and provides hints as you type
- Automatic code formatting based on user-defined rules
- Live parsing

User-Friendly, Customizable Interface:

- Fully customizable interface: toolbars, toolbar buttons, windows, window placement, etc.
- Call graph window

Project-Based Workspaces:

- Multiple projects
- Multiple tools
- Multiple configurations
- Simultaneous debugging sessions

File History and Bug Tracking:

- Local file history feature
- Built-in support for Bugzilla issue tracker

TABLE 30-8: DC CHARACTERISTICS: POWER-DOWN CURRENT (I_{PD})

DC CHARACTERISTICS			Standard Operating Conditions: 4.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ T_A ≤ +85°C for Industrial -40°C ≤ T_A ≤ +125°C for Extended			
Parameter No.	**Typ.**[2]	**Max.**	**Units**	**Conditions**		
Power-Down Current (I_{PD}) – dsPIC33EVXXXGM00X/10X[1]						
DC60d	9.25	30	μA	-40°C	5.0V	Base Power-Down Current
DC60a	15.75	35	μA	+25°C		
DC60b	67.75	250	μA	+85°C		
DC60c	270	750	μA	+125°C		
DC61d	1	7	μA	-40°C	5.0V	Watchdog Timer Current: ΔI_{WDT}[3]
DC61a	1.25	8	μA	+25°C		
DC61b	3.5	12	μA	+85°C		
DC61c	5	15	μA	+125°C		

Note 1: I_{PD} (Sleep) current is measured as follows:

- CPU core is off, oscillator is configured in EC mode and external clock is active, OSC1 is driven with external square wave from rail-to-rail (EC clock overshoot/undershoot < 250 mV required)
- CLKO is configured as an I/O input pin in the Configuration Word
- All I/O pins are configured as outputs and driving low
- $\overline{\text{MCLR}}$ = V_{DD}, WDT and FSCM are disabled
- All peripheral modules are disabled (PMDx bits are all ones)
- The VREGS bit (RCON<8>) = `0` (i.e., core regulator is set to standby while the device is in Sleep mode)
- The VREGSF bit (RCON<11>) = `0` (i.e., Flash regulator is set to standby while the device is in Sleep mode)

2: Data in “Typ.” column is at 5.0V, +25°C unless otherwise stated.

3: The Δ current is the additional current consumed when the module is enabled. This current should be added to the base I_{PD} current.

TABLE 30-35: SPI2 SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 1, SMP = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			**Standard Operating Conditions: 4.5V to 5.5V (unless otherwise stated)** Operating temperature -40°C ≤ T_A ≤ +85°C for Industrial -40°C ≤ T_A ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic[(1)]**	**Min.**	**Typ.[(2)]**	**Max.**	**Units**	**Conditions**
SP70	FscP	Maximum SCK2 Input Frequency	—	—	11	MHz	See **Note 3**
SP72	TscF	SCK2 Input Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP73	TscR	SCK2 Input Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP30	TdoF	SDO2 Data Output Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP31	TdoR	SDO2 Data Output Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP35	TscH2doV, TscL2doV	SDO2 Data Output Valid after SCK2 Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDO2 Data Output Setup to First SCK2 Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI2 Data Input to SCK2 Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDI2 Data Input to SCK2 Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{\text{SS2}}$ ↓ to SCK2 ↑ or SCK2 ↓ Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{\text{SS2}}$ ↑ to SDO2 Output High-Impedance	10	—	50	ns	See **Note 4**
SP52	TscH2ssH TscL2ssH	$\overline{\text{SS2}}$ ↑ after SCK2 Edge	1.5 T_{CY} + 40	—	—	ns	See **Note 4**
SP60	TssL2doV	SDO2 Data Output Valid after $\overline{\text{SS2}}$ Edge	—	—	50	ns	

Note 1: These parameters are characterized but not tested in manufacturing.

2: Data in “Typ.” column is at 5.0V, +25°C unless otherwise stated.

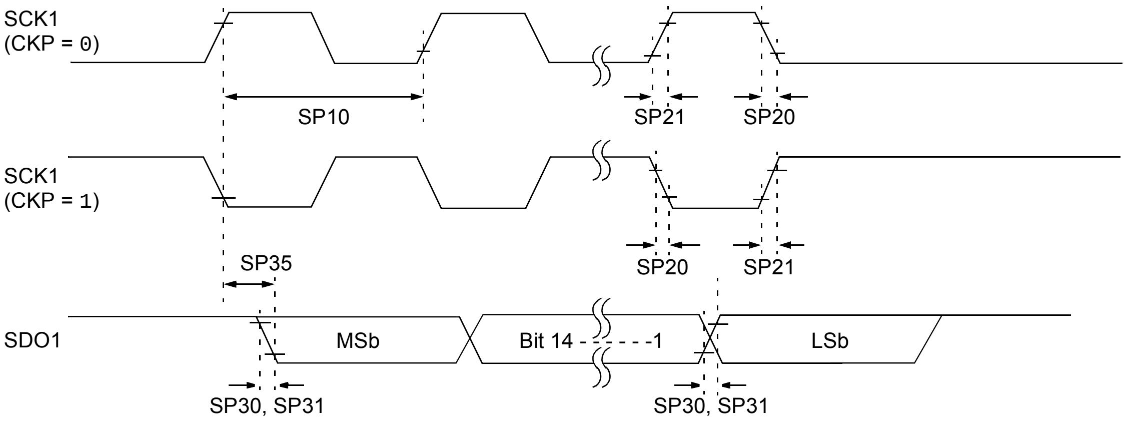
3: The minimum clock period for SCK2 is 91 ns. Therefore, the SCK2 clock generated by the master must not violate this specification.

4: Assumes 50 pF load on all SPI2 pins.

TABLE 30-38: SPI1 MAXIMUM DATA/CLOCK RATE SUMMARY

AC CHARACTERISTICS				**Standard Operating Conditions: 4.5V to 5.5V (unless otherwise stated)** Operating temperature -40°C ≤ T_A ≤ +85°C for Industrial -40°C ≤ T_A ≤ +125°C for Extended		
Maximum Data Rate	**Master Transmit Only (Half-Duplex)**	**Master Transmit/Receive (Full-Duplex)**	**Slave Transmit/Receive (Full-Duplex)**	**CKE**	**CKP**	**SMP**
25 MHz	Table 30-39	—	—	0,1	0,1	0,1
25 MHz	—	Table 30-40	—	1	0,1	1
25 MHz	—	Table 30-41	—	0	0,1	1
25 MHz	—	—	Table 30-42	1	0	0
25 MHz	—	—	Table 30-43	1	1	0
25 MHz	—	—	Table 30-44	0	1	0
25 MHz	—	—	Table 30-45	0	0	0

FIGURE 30-20: SPI1 MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY, CKE = 0) TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

33.8 Pull-up/Pull-Down Current

FIGURE 33-23: TYPICAL PULL-DOWN CURRENT (VPIN = 5.5V) vs. TEMPERATURE

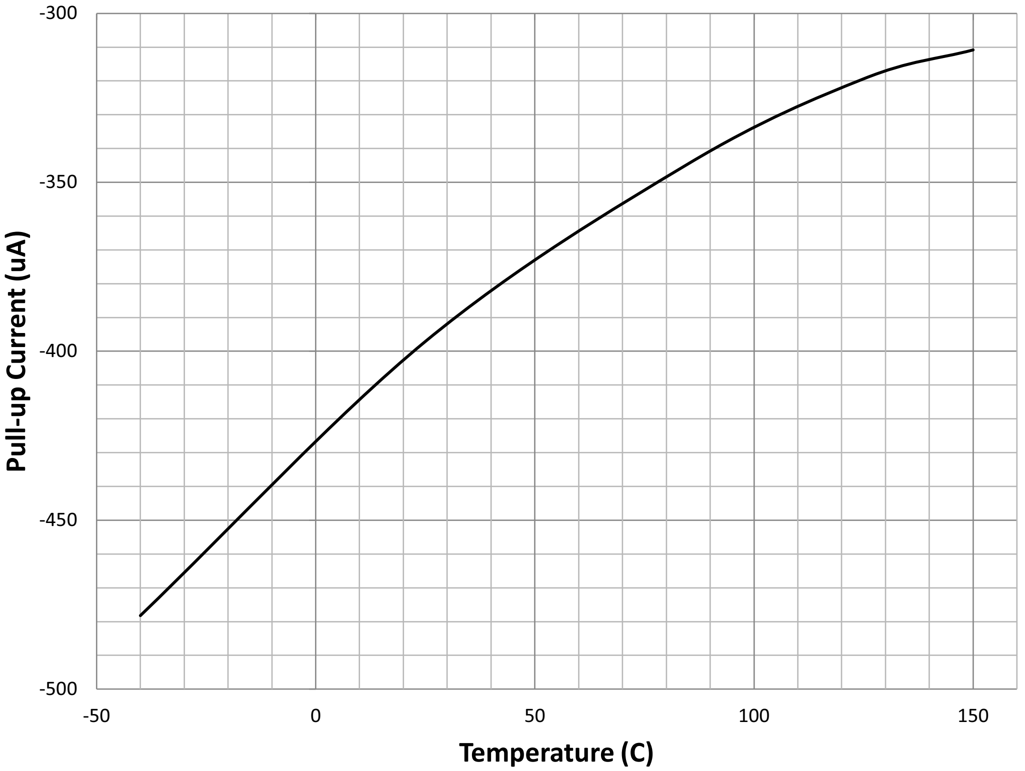
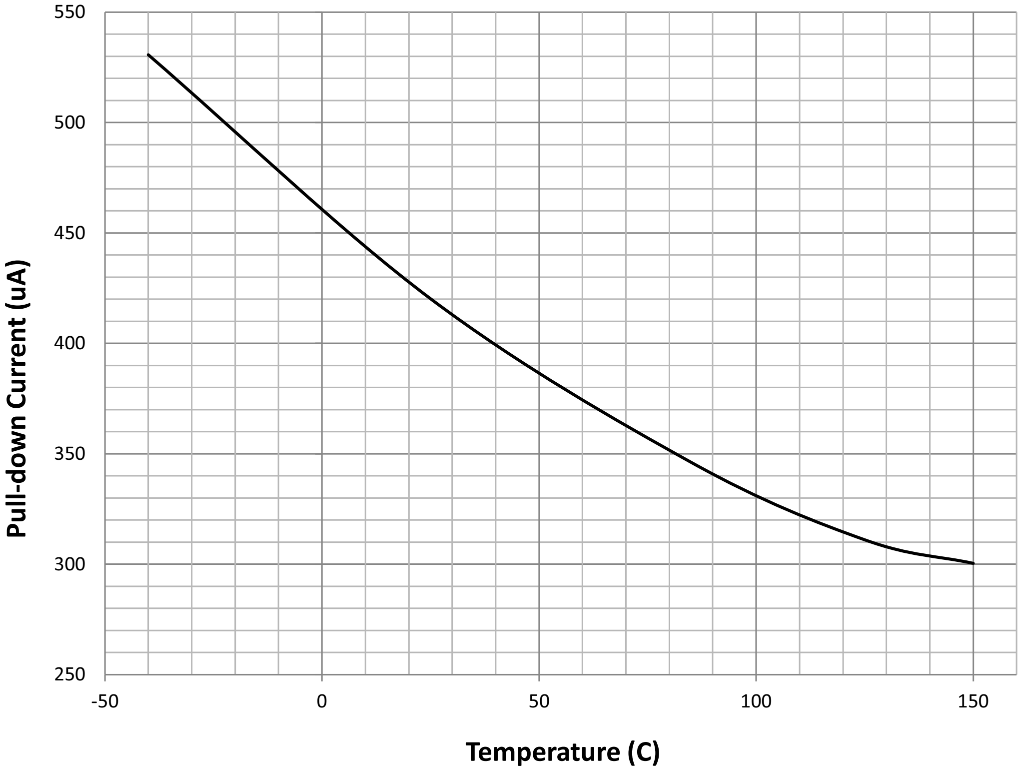
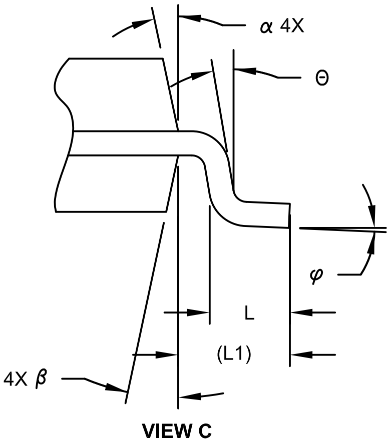


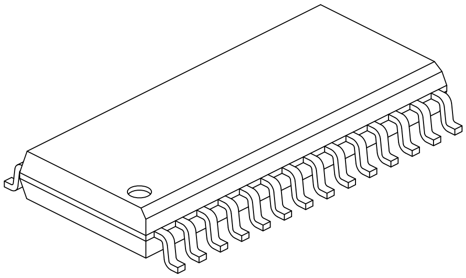
FIGURE 33-24: TYPICAL PULL-DOWN CURRENT (VPIN = 5.5V) vs. TEMPERATURE



28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging





Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N	28		
Pitch	e	1.27 BSC		
Overall Height	A	-	-	2.65
Molded Package Thickness	A2	2.05	-	-
Standoff §	A1	0.10	-	0.30
Overall Width	E	10.30 BSC		
Molded Package Width	E1	7.50 BSC		
Overall Length	D	17.90 BSC		
Chamfer (Optional)	h	0.25	-	0.75
Foot Length	L	0.40	-	1.27
Footprint	L1	1.40 REF		
Lead Angle	Θ	0°	-	-
Foot Angle	φ	0°	-	8°
Lead Thickness	c	0.18	-	0.33
Lead Width	b	0.31	-	0.51
Mold Draft Angle Top	α	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°

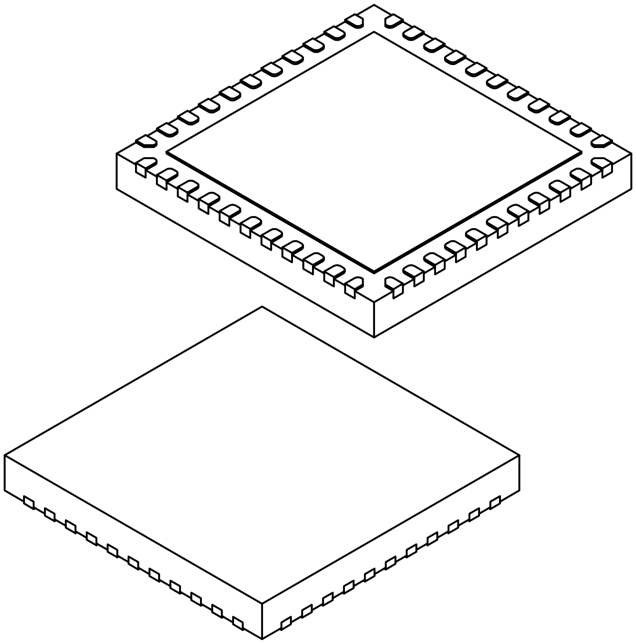
Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic
3. Dimension D does not include mold flash, protrusions or gate burrs, which shall not exceed 0.15 mm per end. Dimension E1 does not include interlead flash or protrusion, which shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only.
5. Datums A & B to be determined at Datum H.

Microchip Technology Drawing C04-052C Sheet 2 of 2

44-Lead Plastic Quad Flat, No Lead Package (ML) - 8x8 mm Body [QFN or VQFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units	MILLIMETERS		
	Dimension Limits	MIN	NOM	MAX
Number of Pins	N		44	
Pitch	e		0.65 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Terminal Thickness	A3		0.20 REF	
Overall Width	E		8.00 BSC	
Exposed Pad Width	E2	6.25	6.45	6.60
Overall Length	D		8.00 BSC	
Exposed Pad Length	D2	6.25	6.45	6.60
Terminal Width	b	0.20	0.30	0.35
Terminal Length	L	0.30	0.40	0.50
Terminal-to-Exposed-Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated
3. Dimensioning and tolerancing per ASME Y14.5M

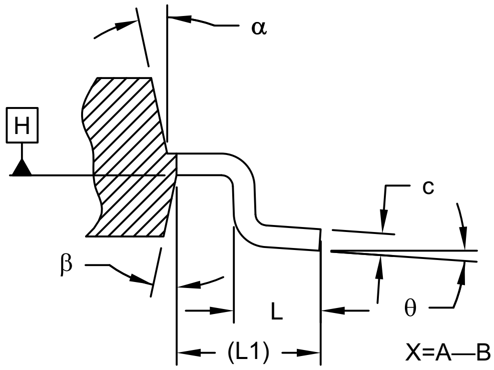
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

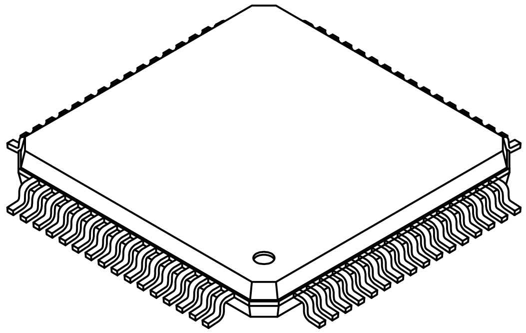
Microchip Technology Drawing C04-103D Sheet 2 of 2

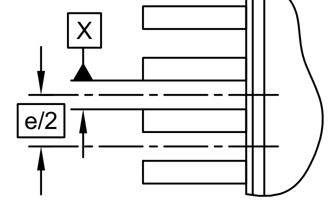
64-Lead Plastic Thin Quad Flatpack (PT)-10x10x1 mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



SECTION A-A





DETAIL 1

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N		64	
Lead Pitch	e		0.50 BSC	
Overall Height	A	-	-	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	-	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1		1.00 REF	
Foot Angle	ϕ	0°	3.5°	7°
Overall Width	E		12.00 BSC	
Overall Length	D		12.00 BSC	
Molded Package Width	E1		10.00 BSC	
Molded Package Length	D1		10.00 BSC	
Lead Thickness	c	0.09	-	0.20
Lead Width	b	0.17	0.22	0.27
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-085C Sheet 2 of 2